

L Number	Hits	Search Text	DB	Time stamp
-	955	(257/737).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/15 18:11
-	453	((257/737).CCLS.) and heat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 10:39
-	127	((257/737).CCLS.) and (heat with (sink spreader) stiffener)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 11:44
-	2	("5481798" "5786239").PN.	USPAT	2002/03/14 10:42
-	21	("5216278" "5239198" "5272375" "5285352" "5311059" "5397917" "5455456" "5468995" "5506755" "5508556" "5561322" "5581122" "5598036" "5640048" "5698896" "5703397" "5729432" "5834848" "5907187" "5909058" "5909633").PN.	USPAT	2002/03/14 10:43
-	5	("5045921" "5184207" "5224264" "5350947" "5420460").PN.	USPAT	2002/03/14 10:47
-	10	("4285002" "4689103" "5159750" "5235209" "5331510" "5357672" "5420460" "5557502" "5572405" "5578796").PN.	USPAT	2002/03/14 10:48
-	60	5420460.URPN.	USPAT	2002/03/14 10:49
-	493	double with heat with sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 11:03
-	92	(double with heat with sink) and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 10:58
-	134	double adj heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 11:03
-	109	(double adj heat adj sink) not ((double with heat with sink) and (257/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 11:04
-	748	(257/706).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 11:07
-	467	((257/706).CCLS.) and (heat with (sink spreader) stiffener)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 11:07
-	456	((((257/706).CCLS.) and (heat with (sink spreader) stiffener)) not (((257/737).CCLS.) and (heat with (sink spreader) stiffener)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/14 11:08

-	9	("4141030" "4340902" "4396935" "4587550" "4620215" "4803546" "4890194" "5012386" "5047837").PN.	USPAT	2002/03/14 13:25
-	23	5175612.URPN.	USPAT	2002/03/14 13:26
-	92	(IC die semiconductor) with second adj heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:29
-	52	((IC die semiconductor) with second adj heat adj sink) not (chip with second adj heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:32
-	837	(257/717).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:32
-	412	((257/717).CCLS.) and (heat with (sink spreader) stiffener slung)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:33
-	32	((257/717).CCLS.) and wire and ball and (PCB board grid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:34
-	71	((257/717).CCLS.) and (heat with (sink spreader) stiffener slung)) and wire and (PCB board grid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:35
-	71	((257/717).CCLS.) and (heat with (sink spreader) stiffener slung)) and wire and (PCB board grid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 16:09
-	0	BGA and tape with poyimide with substrat and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 16:10
-	0	BGA and tape with poyimide with substrat and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 16:10
-	0	BGA and tape with poyimide with substrate and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 16:11
-	204	BGA and tape with substrate and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 17:32
-	27	(chip die) with wire with heat with ground and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/15 09:16
-	0	"pair of heat sinks"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/15 09:18

-	241	pair adj heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/15 12:20
-	2	5737272.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/15 12:20
-	2	6184580.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/15 18:18
-	2	heat with sink with wire with ground with better	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/15 18:19



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3	NPL	10

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